



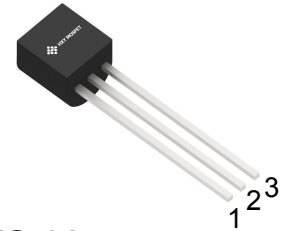
Features

- Power dissipation
 $P_C : 1W \quad (T_a=25^{\circ}C)$

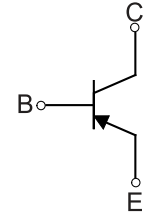
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SS8550	TO-92	HXY MOSFET	1000

- EMITTER
- BASE
- COLLECTOR



TO-92



Maximum Ratings ($T_a=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	-40	V
V_{CEO}	Collector-Emitter Voltage	-25	V
V_{EBO}	Emitter-Base Voltage	-5	V
I_C	Collector Current	-1.5	A
P_C	Collector Power Dissipation	1	W
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	125	$^{\circ}C/W$
T_J, T_{stg}	Operation Junction and Storage Temperature Range	-55~+150	$^{\circ}C$

Electrical Characteristics($T_a=25^{\circ}C$ unless otherwise specified)

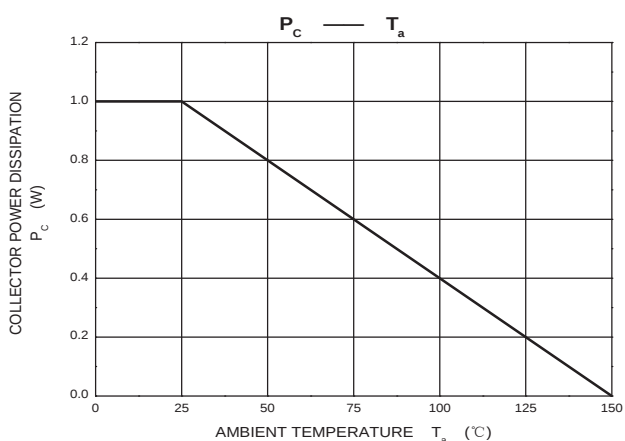
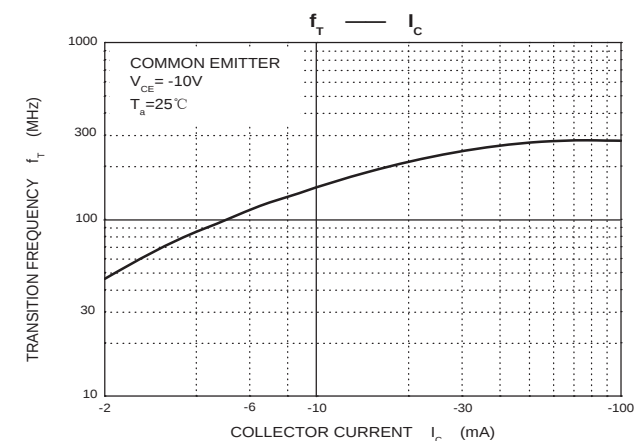
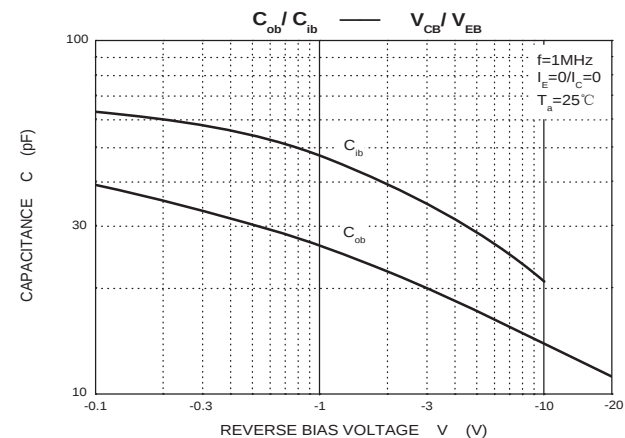
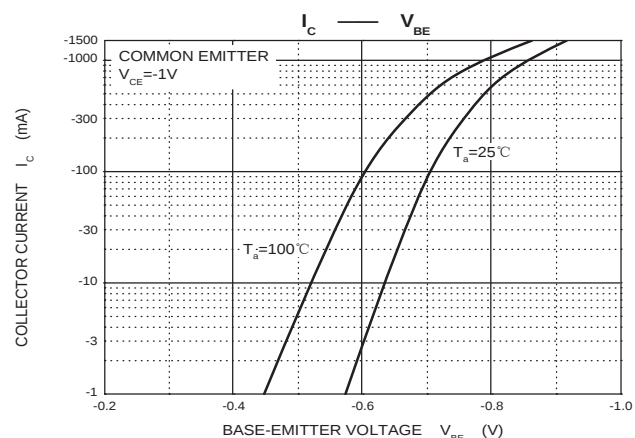
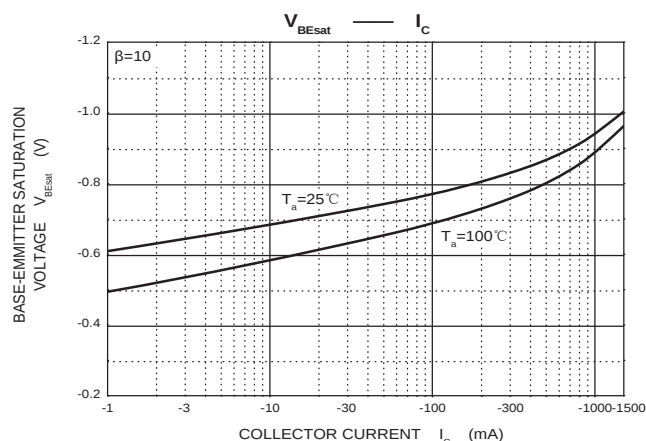
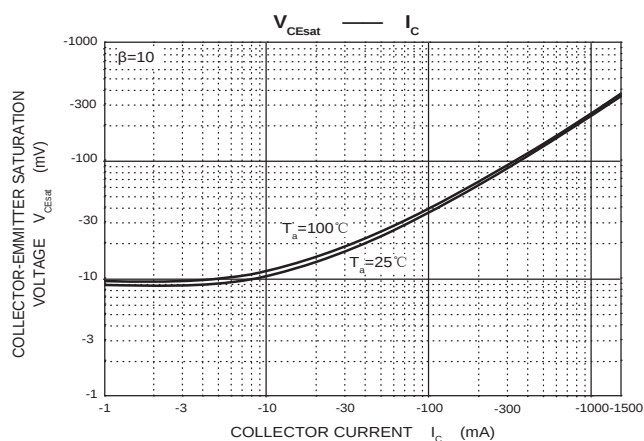
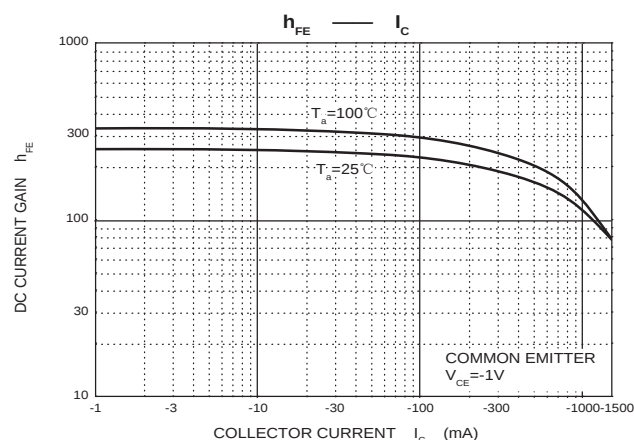
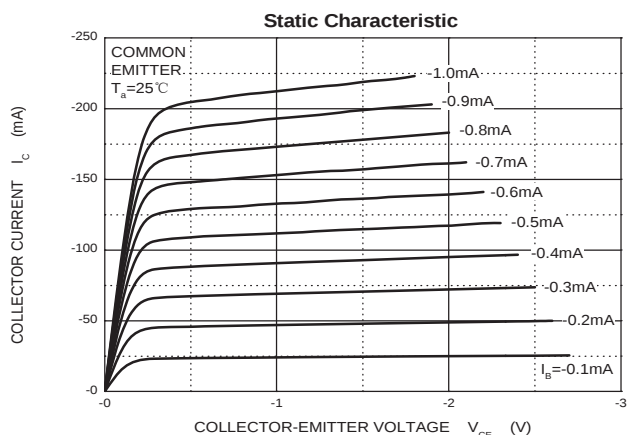
Parameter	Symbol	Test conditions	Min	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=-100\mu A, I_E=0$	-40		V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C=-0.1mA, I_B=0$	-25		V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=-100\mu A, I_C=0$	-5		V
Collector cut-off current	I_{CBO}	$V_{CB}=-40V, I_E=0$		-0.1	μA
Emitter cut-off current	I_{CEO}	$V_{CE}=-20V, I_E=0$		-0.1	μA
Emitter cut-off current	I_{EBO}	$V_{EB}=-5V, I_C=0$		-0.1	μA
DC current gain	$h_{FE(1)}$	$V_{CE}=-1V, I_C=-100mA$	85	400	
	$h_{FE(2)}$	$V_{CE}=-1V, I_C=-800mA$	40		
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=-800mA, I_B=-80mA$		-0.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C=-800mA, I_B=-80mA$		-1.2	V
Base-emitter voltage	$V_{BE(on)}$	$V_{CE}=-1V, I_C=-10mA$		-1	V
Out capacitance	C_{Ob}	$V_{CB}=-10V, I_E=0mA, f=1MHz$		20	pF
Transition frequency	f_T	$V_{CE}=-10V, I_C=-50mA, f=30MHz$	100		MHz

Classification Of $h_{FE(1)}$

Rank	B	C	D	D3
Range	85-160	120-200	160-300	300-400

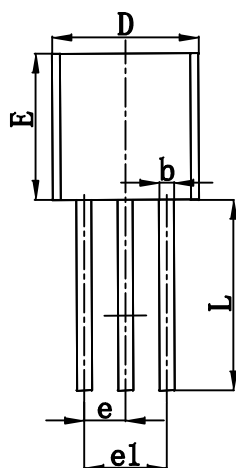
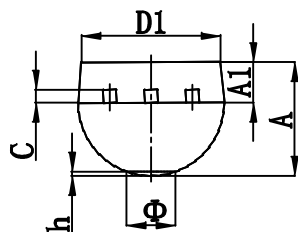


Typical Characteristics



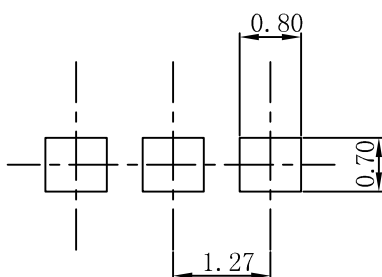


TO-92 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	3.300	3.700	0.130	0.146
A1	1.100	1.400	0.043	0.055
b	0.380	0.550	0.015	0.022
c	0.360	0.510	0.014	0.020
D	4.300	4.700	0.169	0.185
D1	3.430		0.135	
E	4.300	4.700	0.169	0.185
e	1.270 TYP		0.050 TYP	
e1	2.440	2.640	0.096	0.104
L	14.100	14.500	0.555	0.571
Φ		1.600		0.063
h	0.000	0.380	0.000	0.015

TO-92 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.



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